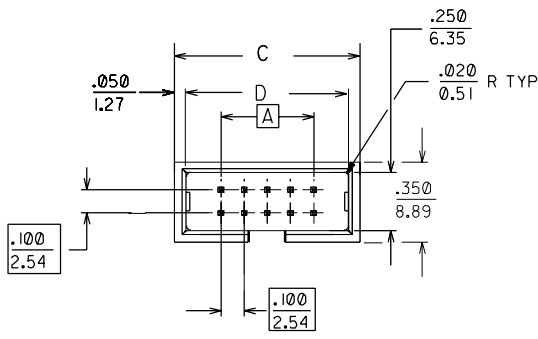
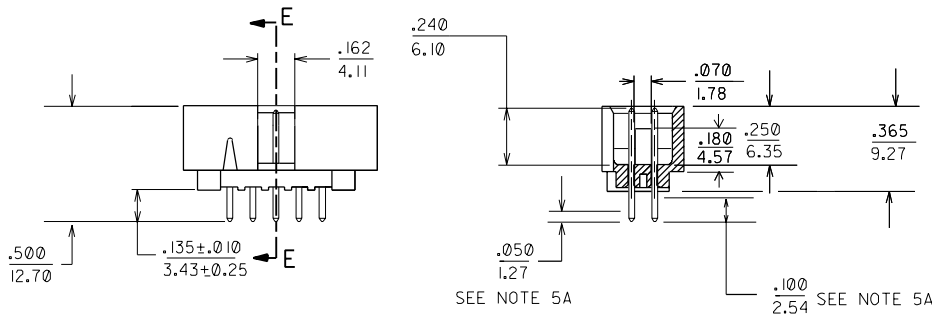
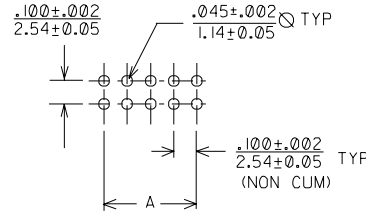


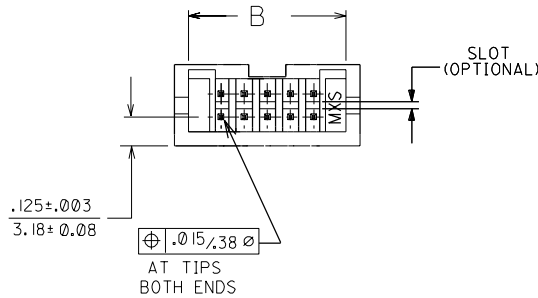
DWG. NO. SDA 70246-***45-52,57,62
 CAD FILE S7024645.DGN



RECOMMENDED P.C. BOARD HOLE LAYOUT



SECTION E-E



70246-***

CKT SIZE

45 - 573	49 - 146
46 - 571	50 - 608
47 - 574	51 - 817
48 - 816	52 - 818
57 - 814	62 - 820

ASSEMBLY TYPE

PART NO.	CKT SIZE	A	B	C	D
70246 - 08**	08	0.300/7.62	0.580/14.73	0.700/17.78	0.600/15.24
70246 - 10**	10	0.400/10.16	0.680/17.27	0.800/20.32	0.700/17.78
70246 - 12**	12	0.500/12.70	0.780/19.81	0.900/22.86	0.800/20.32
70246 - 14**	14	0.600/15.24	0.880/22.35	1.000/25.40	0.900/22.86
70246 - 16**	16	0.700/17.78	0.980/24.89	1.100/27.94	1.000/25.40
70246 - 20**	20	0.900/22.86	1.180/29.97	1.300/33.02	1.200/30.48
70246 - 24**	24	1.100/27.94	1.380/35.05	1.500/38.10	1.400/35.56
70246 - 26**	26	1.200/30.48	1.480/37.59	1.600/40.64	1.500/38.10
70246 - 30**	30	1.400/35.56	1.680/42.67	1.800/45.72	1.700/43.18
70246 - 34**	34	1.600/40.64	1.880/47.75	2.000/50.80	1.900/48.26
70246 - 40**	40	1.900/48.26	2.180/55.37	2.300/58.42	2.200/55.88
70246 - 44**	44	2.100/53.34	2.380/60.45	2.500/63.50	2.400/60.96
70246 - 50**	50	2.400/60.96	2.680/68.07	2.800/71.12	2.700/68.58
70246 - 56**	56	2.700/68.58	2.980/75.69	3.100/78.74	3.000/76.20
70246 - 60**	60	2.900/73.66	3.180/80.77	3.300/83.82	3.200/81.28
70246 - 64**	64	3.100/78.74	3.380/85.85	3.500/88.90	3.400/86.36
70246 - 72**	72	3.500/88.90	3.780/96.01	3.900/99.06	3.800/96.52

NOTES:

- PIN PUSHOUT FORCE (9072KG)/2LBS MIN.
- PIN SOLDERABILITY PER MOLEX SPEC. ES-152
- PRODUCT SPEC: PS-70246 APPLIES.
- WAFER TO BE FLAT WITHIN (0.03MM/CM) 0.003IN/IN
- DIMENSIONS FOR PLATING LOCATION : A-MEASURE POINT FOR THICKNESS. B-MINIMUM COVERAGE
- GOLD END OF PIN UNLESS OVERALL PLATED.
- FINISH : (PER ES-88) (ALL WITH 50µin MIN NICKEL UNDERPLATE OVERALL.)
 573 - 20µin MIN AU & 100µin MIN TIN/LEAD IN SELECTED AREAS.
 571 - 15µin MIN AU & 75µin MIN TIN/LEAD IN SELECTED AREAS.
 574 - 30µin MIN AU & 75µin MIN TIN/LEAD IN SELECTED AREAS.
 146 - 200µin MIN TIN/LEAD.
 608 - 5µin MIN AU & 75µin MIN TIN/LEAD IN SELECTED AREAS.
 816 - GOLD FLASH OVER 15µin MIN PD/NI & 75µin MIN TIN/LEAD IN SELECTED AREAS.
 817 - GOLD FLASH OVER 30µin MIN PD/NI & 75µin MIN TIN/LEAD IN SELECTED AREAS.
 818 - GOLD FLASH OVER 50µin MIN PD/NI & 75µin MIN TIN/LEAD IN SELECTED AREAS.
 814 - 5µin MIN AU OVER 40µin MIN PD/NI & 100µin MIN TIN/LEAD IN SELECTED AREAS.
 820 - 5µin MIN AU OVER 100µin MIN PD/NI & 100µin MIN TIN/LEAD IN SELECTED AREAS.

INCH
MM

B3	REL. PER ECN*S1998-0467.		LPT	980330
B2	REVISED PLATING CODE.	S40403	SEE TOH	940214
B1	CHG PIN MAT'L OPT	S1405	KHD ANG	910219
B	ADD **62	OS043	JEN AB	890807
A	REL TO MFG	9S157	JEN AB	890525
3	ADD **57 & CKT 30	9S091	JEN AB	890328
2	CHG HSC PER ERO*	9S046	JEN AB	890209
1	X-REL PER ERO*	8S286	JEN ROY	881228
LTR	REVISION RECORD	ECN	DR	CHK

MATERIAL :	HSG: 30% G.F. POLYESTER, 94V-0.
COLOUR :	BLACK.
PIN:	0.64mm SQ. PIN PHOSPHOR BRONZE.
FINISH :	SEE NOTE 7
DRAWN BY	JENNIFER 881228
CHK'D BY	ROY WONG 881228
APPR'D BY	ALAN BERG 881228
SCALE	2 : 1

MOLEX SINGAPORE PTE LTD
 SHEET 1 OF 1

GENERAL TOLERANCES ± 0.20/0.008 REV B3

DWG. NO.: SDA | 70246-***45-52,57,62

TITLE : ASSY, C-GRID, SHROUDED HEADER, WINDOW W/ END SLOTS (SLOTTED WITHOUT STANDOFFS)

REVISE ONLY ON CAD SYSTEM

DO NOT SCALE DRAWING